

Data sheet acquired from Harris Semiconductor SCHS035C – Revised September 2003

### **CMOS Quad Exclusive-OR Gate**

High-Voltage Types (20-Volt Rating)

■ CD4030B types consist of four independent Exclusive-OR gates. The CD4030B provides the system designer with a means for direct implementation of the Exclusive-

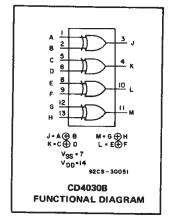
The CD4030B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

## CD4030B Types

#### Features:

- Medium-speed operation—tpHL, tpLH = 65 ns (typ.) at  $V_{DD} = 10 \text{ V, C}_{L} = 50 \text{ pF}$
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 µA at 18 V over full packagetemperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):

■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



#### Applications:

- Even and odd-parity generators and checkers
- Logical comparators
- Adders/subtractors
- General logic functions

MAXIMUM RATINGS, Absolute-Maximum Values:

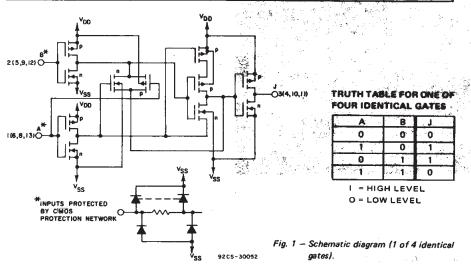
DC SUPPLY-VOLTAGE RANGE, (VDD) Voltages referenced to VSS Terminal) ......-0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS ......-0.5V to V<sub>DD</sub> +0.5V DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA POWER DISSIPATION PER PACKAGE (PD): For T<sub>A</sub> = +100°C to +125°C...... Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) . . . . . . . . 100mW

OPERATING-TEMPERATURE RANGE (TA).....-55°C to +125°C STORAGE TEMPERATURE RANGE (T<sub>stg</sub>).....-65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING): At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ...... +265°C

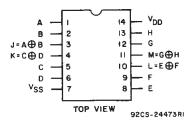
#### **RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIM			
CHARACTERISTIC	MIN.	MAX.	UNITS	
Supply-Voltage Range (For T <sub>A</sub> = Full Package: Temperature Range)	3.	. 18	,	



#### **TERMINAL DIAGRAM** Top View



### CD4030B Types

#### STATIC ELECTRICAL CHARACTERISTICS

CHARAC-	CONI	OITIO	NS	LIMITS AT INDICATED TEMPERATURES (°C)							U
TERISTIC	v <sub>o</sub>	VIN	VDD						+25	,	т
	(V)	(V)	(V)	<b>–55</b>	<del>-40</del>	+85	+125	Min.	Тур.	Max.	S
Quiescent		0,5	5	0.25	0.25	7.5	7.5		0.01	0.25	
Device	_	0,10	10	0.5	0.5	15	15	-	0.01	0.5	$\mu$
Current, I <sub>DD</sub>		0,15	15	1	1	30	30	-	0.01	1	
Max.	-	0,20	20	5	5	150	150	_	0.02	5	
Output Low (Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_	
Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_	
Output High	4.6	0,5	5	-0.64	-0.61	0.42	-0.36	-0.51	-1	-	'n
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	ŀ
Current,	9.5	0,10	10	-1.6	1.5	-1.1	-0.9	-1.3	-2.6		1
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		1
Output Voltage:	_	0,5	5		0	.05	_	0	0.05	Γ	
Low-Level,		0,10	10		0	.05	_		0.05	]	
VOL Max.	-	0,15	15		0	.05		-	0	0.05	],
Output Voltage:	_	0,5	5		4	.95	4.95	5		1	
High-Level,	_	0,10	10		9	.95	9.95	10	_	1	
V <sub>OH</sub> Min.	_	0,15	15		14	.95	14.95	15	_	1	
Input Low	0.5,4.5	ı	5		1	.5	_	_	1.5		
Voltage,	1,9	-	10			3	_	-	3		
V <sub>IL</sub> Max.	1.5,13.5	-	15			4	-	_	4	١,	
Input High	0.5,4.5	_	5			3.5	3.5	_	_	]	
Voltage,	1,9	_	10			7	. 7		-		
V <sub>1H</sub> Min.	1.5,13.5	_	15			11		11	_		
Input Current IN Max.	_	0,18	18	±0.1	±0.1	±1	±1	_	±10 <sup>-5</sup>	±0.1	1

# DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C; Input t $_r$ , t $_f$ = 20 ns, C $_L$ = 50 pF, R $_L$ = 200 K $\Omega$

	CONDITIONS	LIMITS		UNITS		
CHARACTERISTIC					V <sub>DD</sub>	
	(V)	Тур.	Max.			
	-	5	140	280		
Propagation Delay Time,	tPLH, tPHL	10	65	130	ns	
		15	50	100		
Transition Time,		5	100	200	_	
	tTHL, tTLH	10	50	100	ns	
		15	40	80	1	
Input Capacitance,	CIN	Any Input	5	7.5	ρF	

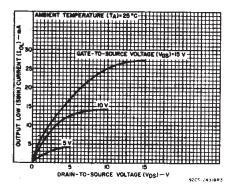


Fig. 2 — Typical output low (sink) current characteristics.

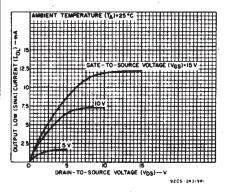


Fig. 3 – Minimum output low (sink) current characteristics.

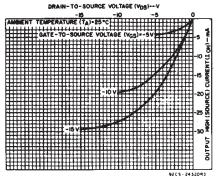


Fig. 4 — Typical output high (source) current characteristics.

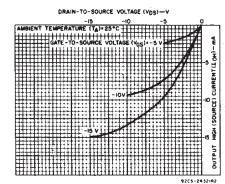


Fig. 5 – Minimum output high (source) current characteristics.

### CD4030B Types

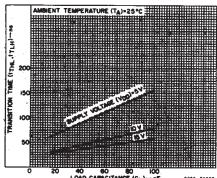


Fig. 6 — Typical transition time as a function of load capacitance.

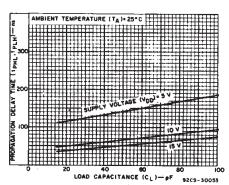


Fig. 7 — Typical propagation delay time as a function of load capacitance.

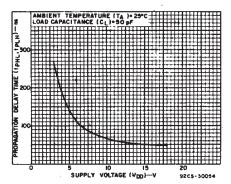


Fig. 8 — Typical propagation delay time as a function of supply voltage.

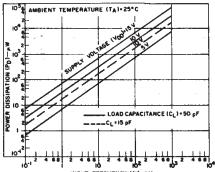


Fig. 9 — Typical dynamic power dissipation as a function of input frequency.

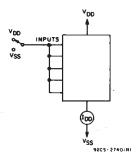


Fig. 10 - Quiescent-device current test circuit.

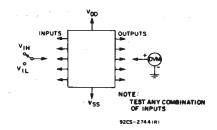


Fig. 11 — Input-voltage test circuit.

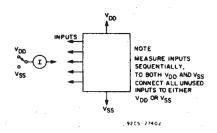


Fig. 12 - Input-current test circuit.

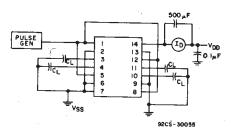
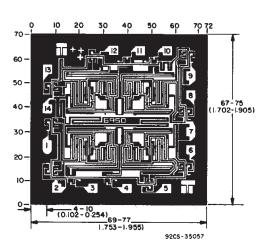


Fig. 13 – Dynamic power dissipation test circuit.



Dimensions and pad layout for CD4030BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).





i.com 26-Sep-2005

#### **PACKAGING INFORMATION**

Orderable Dev	rice Status <sup>(1</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD4030BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4030BEE	4 ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4030BF	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
CD4030BF3	A ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
CD4030BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BM9	6 ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BM96	E4 ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BME	4 ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BM7	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BMTE	4 ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BNS	R ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BNSR	E4 ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BPV	V ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BPWI	E4 ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BPW	R ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4030BPWR	E4 ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
JM38510/05353	BCA ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



### PACKAGE OPTION ADDENDUM

26-Sep-2005

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### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

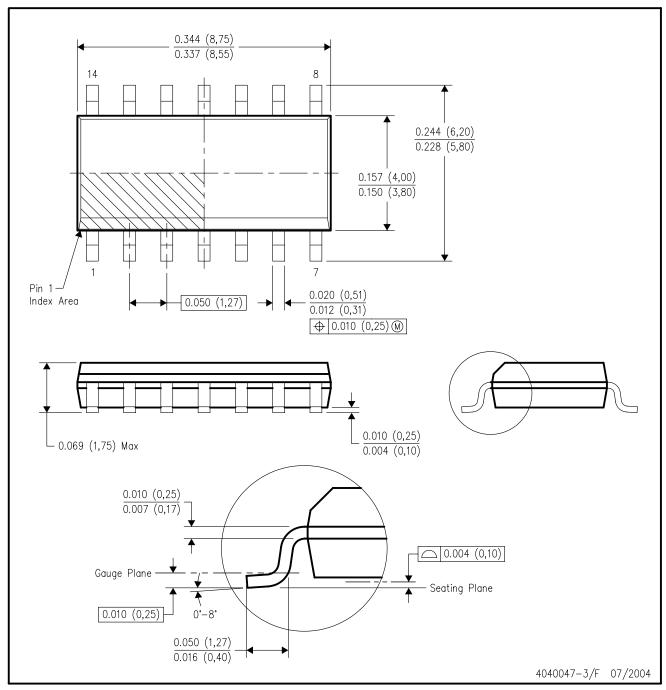


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDSO-G14)

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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